



## **MF Magnetron Sputtering Coating Machine**



The series of the equipments gradually play a leading role technique of supttering coating field. The reason why this machine advantage with DC sputtering coating characteristic

- 1) Surmount anode disppear phenomenon
- Recede or eliminate abnormal arc light discharge of target Therefore, its had advanced performance stability of sputtering processing and deposit rate of dielectric film.

We had developed plane target, columnar target, twin targets etc. MF sputtering target structure and layout. It is widely used in the watchband, watchcase, mobile shell, hardware tableware etc. It can coat TiN, TiC, TiCN, TiAIN, TrN, Cu, Au, and other decorative films.

Products











## PARAMETER DESCRIPTION

| Mode                                 | JTL - 1090  | JTL - 1110  | JTL - 1312  |
|--------------------------------------|---|---|---|
| Dimension                            | Ф1000 x 900mm   | Ф1100 x 1000mm  | Ф1300 x 1200mm  |
| Coating mode and main continguration | 6 multi-arc targets +one<br>set of columnar targets +<br>a pair of plane<br>rectangular targets                     | 6 multi -arc targets +a pair of<br>twins (MF) Sputtering targets<br>+a pair of plane rectangular<br>cathode | 8 electric-arc+2 pairs of plane rectangular targets +a pair of twins (MF) sputtering targets. |
| Film Types                           | Metal films, Dielectric films, Compound films, Reaction Films, Muti-layer function films                            |   |   |
| Power Source                         | DC magnetron power supply, MF magnetron power supply pulse bias voltage power supply, icon source power supply      |   |   |
| Vacuum chamber Structure             | Pre-open vertical (Single) door, postposition pump system, double water-cooling                                     |   |   |
| Vacuum System                        | Molecule Pump (diffusion pump) + Roots Pump + Mechanical pump 8.0x10 <sup>4</sup> pa                                |   |   |
| Pumping Speed                        | 8.0x10 <sup>3</sup> pa<15min Pumping time less than 15 minutes, from atmospheric ptessure to 3.0x10 <sup>5</sup> pa |   |   |
| Movement of the workpiece            | Variable frequency speed adjustable   |   |   |
| Baking temperature of the workpiece  | Adjustable and contrillable from room temperature to 350°C, radiation heating                                       |   |   |
| control mode                         | Full automation control system PC+PLC/PC+HM   |   |   |
| Remark                               | We can design the machine according to your workpiece and special technological requirement                         |   |   |

## **Products**











